PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/25/15422
1.3 Title of PCN	ASE KaoHsiung (Taiwan) additional source for STM32F74/75xx, STM32F76/77xx listed products in TFBGA 13X13 216L package and STM32F20/21xx, STM32F40/41xx, STM32F42/43xx listed products in UFBGA 10X10 176+25 package.
1.4 Product Category	STM32F74/75xx, STM32F76/77xx, STM32F20/21xx, STM32F40/41xx and STM32F42/43xx
1.5 Issue date	2025-09-16

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE KaoHsiung (Taiwan)

4. Description of change		
	Old	New
4.1 Description	Current assembly sites (depending on package/product): - AMKOR ATP (Philippine) Gold for Crolles, TSMC & Rousset Dice, - AMKOR ATP (Philippine) Copper Palladium wire for Crolles, TSMC Dice, - ASE Kaohsiung (Taiwan) Gold wire for Crolles, TSMC & Rousset Dice, - ASE Kaohsiung (Taiwan) Copper Palladium wire for Crolles & TSMC Dice, You may refer to 15422_Additional information.pdf document for further details.	Current assembly sites: (depending on package/product): - AMKOR ATP (Philippine) Gold for Crolles, TSMC & Rousset Dice, - AMKOR ATP (Philippine) Copper Palladium wire for Crolles, TSMC Dice, - ASE Kaohsiung (Taiwan) Gold wire for Crolles, TSMC & Rousset Dice, - ASE Kaohsiung (Taiwan) Copper Palladium wire for Crolles & TSMC Dice, Additional assembly site for extended capacity: - ASE Kaohsiung (Taiwan) Copper Palladium wire for Rousset Dice.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on Form, Fit or Function	

5. Reason / motivation for change	
5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	Change is visible in the marking. Please refer to PCN 15422_Additional information.pdf document for further details.

7. Timing / schedule	
7.1 Date of qualification results	2025-10-07
7.2 Intended start of delivery	2025-11-07

7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	15422 MDRF-GPAM-RER2520 PCN15422- ASEKH TFBGA216L and UFBGA176+25- Reliability Plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2025-09-16

9. Attachments (additional documentations)
15422 Public product.pdf 15422 MDRF-GPAM-RER2520 PCN15422- ASEKH TFBGA216L and UFBGA176+25- Reliability Plan.pdf 15422 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32F207ICH6	
	STM32F207IEH6	
	STM32F207IFH6	
	STM32F207IGH6	
	STM32F207IGH7	
	STM32F217IEH6	
	STM32F217IGH6	
	STM32F407IEH6	
	STM32F407IGH6	
	STM32F407IGH6TR	
	STM32F407IGH7	
	STM32F417IEH6	
	STM32F417IGH6	
	STM32F427IGH6	
	STM32F427IGH7	
	STM32F427IIH6	
	STM32F427IIH6TR	
	STM32F427IIH7	
	STM32F429IEH6	
	STM32F429IGH6	
	STM32F429IIH6	
	STM32F429IIH6TR	
	STM32F437IGH6	
	STM32F437IIH6	
	STM32F439IGH6	
	STM32F439IIH6	
	STM32F439IIH7	
	STM32F746NEH6	
	STM32F746NGH6	
	STM32F746NGH7	
	STM32F750N8H6	
	STM32F756NGH6	
	STM32F765NGH6	
	STM32F765NGH7	
	STM32F765NIH6	
	STM32F765NIH7	
	STM32F767NGH6	

	STM32F767NIH6	
	STM32F767NIH6TR	
	STM32F767NIH7	
	STM32F769NGH6	
	STM32F769NIH6	
	STM32F777NIH6	
	STM32F779NIH6	
	STM32F779NIH6TR	

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